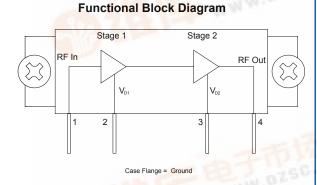


Product Description

The **XD010-04S-D4F** 10W power module is a robust broadband 2-stage Class A/AB amplifier, suitable for use as a power amplifier driver or output stage. It is a drop-in, no-tune, solution for high power applications requiring high efficiency, excellent linearity, and unit to unit repeatability. Internal bias current compensation ensures stable performance over a wide temperature range.



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Preliminary

XD010-04S-D4F

350-600 MHz Class AB 10W Power Amplifier Module

Product Features

- 50 Ω RF Impedance
- > 10W Output P_{1dB}
- Single Voltage Operation
- High Gain: 32 dB Typical
- Temperature Compensation
- Robust 8000V ESD (HBM), Class 3B

Applications

- DTV
- Public Service
- Wireless Infrastructure
- Military
- CDMA or GSM

Parameter	Test Conditions: $ \begin{array}{ll} Z_{in} = Z_{out} = 50 \Omega, \ V_D = 28.0V, \ I_{D1} = 230 m A, \\ = 150 m A, \ T_{Flange} = 25^{\circ} C \end{array} \hspace{1.5cm} I_{D2} $	Unit	Min.	Тур.	Max.
Frequency	Frequency of Operation	MHz	350	1	600
P _{1dB}	Output Power at 1dB Compression, 450MHz	W		12	A DAY
Gain	Gain at 10W Output Power, 450MHz	dB	30	32	
Gain Flatness	Peak to Peak Gain Variation, 350 - 600MHz	dB		1.0	2.0
IRL	Input Return Loss 1W Output Power, 350 - 600MHz	dB	10	15	-
Efficiency	Drain Efficiency at 10W CW, 350-600MHz	%	26	30	-
Linearity	3 rd Order IMD at 10W PEP (Two Tone), 450MHz & 451MHz	dBc	-	-32	-28
Delay	Signal Delay from Pin 1 to Pin 4	nS	-	2.5	-
Phase Linearity	Deviation from Linear Phase (Peak to Peak)	Deg	-	0.5	-

Quality Specifications

Key Specifications

	Parameter		Unit	Min	Typical	Мах
	ESD Rating	Human Body Model, JEDEC Document - JESD22-A114-B	V	8000	-	-
	MTTF	85°C Baseplate, 200°C Channel	Н	-	1.2 X 10 ⁶	-
EA	R _{TH, j-l}	Thermal Resistance Stage 1 (Junction to Case)	°C/W	-	11	-
٢	77 RTH, 12	Thermal Resistance Stage 2 (Junction to Case)	°C/W	-	4	-

The promation provided herein is believed to be reliable at press time. Sirenza Microdevices assumes no responsibility for inaccuracies or ommisions.

Step2a Microdevices assumes no responsibility for the use of this information, and all such information shall be entirely at the user's own risk. Prices and specifications are subject to change without notice. No patenting the checked to any of the circuits described herein are implied or granted to any third party. Sirenza Microdevices does not authorize or warrant any Sirenza Microdevices product for use in life-support devices and/or systems.

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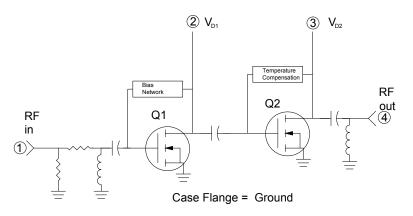
Preliminary

XD010-04S-D4F 350-600 MHz 10W Amp

Pin Description

Pin #	Function	Comments	
1	RF Input	Internally connected to DC ground. Do not apply DC voltages to the RF leads.	
2	V _{D1}	1 st stage bias	
3	V _{D2}	2 nd stage bias. Integrated temperature compensation maintains constant current over the operating tempera- ture range. See Note 1.	
4	RF Output	Internally connected to DC ground. Do not apply DC voltages to the RF leads.	
Flange	Gnd	Baseplate provides electrical ground and a thermal transfer path for the device. Proper mounting assures opti- mal performance and the highest reliablility. See Sirenza applications note: AN-060 Installation Instructions for XD Module Series.	

Simplified Device Schematic



Absolute Maximum Ratings

Parameters	Value	Unit
1 st Stage Bias Voltage (V _{D1})	35	V
2 nd Stage Bias Voltage (V _{D2})	35	V
RF Input Power	+20	dBm
Load VSWR for Continuous Operation With- out Damage	5:1	VSWR
Device Channel Temperature	+200	°C
Lead Temperature During Solder Reflow	+210	°C
Operating Temperature Range	-20 to +90	°C
Storage Temperature Range	-40 to +100	°C

Operation of this device beyond any one of these limits may cause permanent damage. For reliable continuous operation refer to the key specifications table on the first page of the datasheet.

Note 1:

The internally generated gate voltage is thermally compensated to maintain constant drain quiescent current over the temperature range listed in the data sheet. No compensation is provided for gain changes with temperature. This can only be provided with an external AGC circuit.

Note 2:

Internal RF decoupling is included on all bias leads. No additional bypass elements are required, however some applications may require energy storage on the V_D leads to accommodate modulated signals.



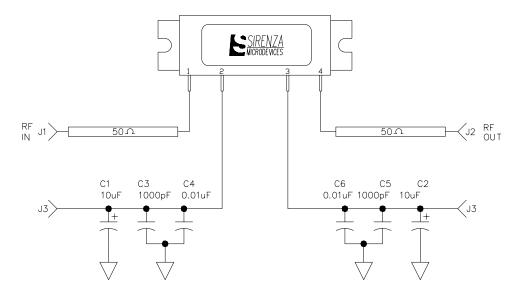
Caution: ESD Sensitive

Appropriate precautions in handling, packaging and testing devices must be observed.

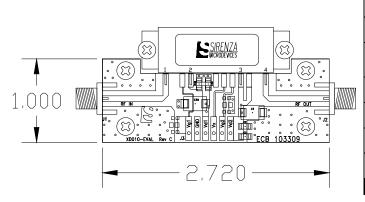


Preliminary XD010-04S-D4F 350-600 MHz 10W Amp

Test Board Schematic with module attachments shown



Test Board Layout and Bill of Materials



Description	Manufacturer	
Rogers4350, ε _r =3.5 Thickness=30mils	Rogers	
SMA, RF, PCB Mount Tab W / Flange	Johnson	
MTA Post Header, 6 Pin, Rectangle, Polarized, Surface Mount	AMP	
Cap, 10µF 50V, 10%, Tant, D	Kemet	
Cap, 0.01µ/F, 100V, 10%, 1206	Johanson	
Cap, 1000pF, 100V, 10%, 1206	Johanson	
4-40 X 0.250"	Various	
	Rogers 4350, ε ₁ =3.5 Thickness=30mils SMA, RF, PCB Mount Tab W / Flange MTA Post Header, 6 Pin, Rectangle, Polarized, Surface Mount Cap, 10μ/F 50V, 10%, Tant, D Cap, 0.01μ/F, 100V, 10%, 1206 Cap, 1000pF, 100V, 10%, 1206	

Gerber files, DXF drawings, a detailed BOM, and assembly recommendations for the test board with fixture are available from Sirenza applications. This datasheet has been download from :

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